Teijin DuPont Films

Innovation for Growth

TECHNICAL DATA

Teonex®
Q83

■Characteristics

Extremely low heat shrinkage type treated by off-line process. Capability for soldering

■Typical Applications

FPC, RFID, Heat label, processing film for semiconductor

■Pretreatment

none

■Technical Data

Item		Unit	Q83 Type	Test method
Thickness		μm	50	JIS C2151
Tensile strength	MD	MPa	270	JIS C2318
	TD		270	
Tensile elongation	MD	%	90	JIS C2318
	TD		90	
Thermal Shrinkage (150 deg C × 30 mins.)	MD	%	0.0	JIS C2318
	TD		0.0	
Thermal Shrinkage (200 deg C × 10 mins.)	MD	%	0.2	JIS C2318
	TD		0.0	
Breakdown voltage		kV/mm	250	JIS C2318
Coefficient of friction	μs	–	0.4	JIS C7175
	μk		0.3	
Haze		%	15.0	JIS C7361

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